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SN74AVC16T245 16-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS

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FEATURES

- Control Inputs V_{IH}/V_{IL} Levels Are Referenced to V_{CCA} Voltage
- V_{CC} Isolation Feature If Either V_{CC} Input Is at GND, Both Ports Are in the High-Impedance State
- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- Fully Configurable Dual-Rail Design Allows Each Port to Operate Over the Full 1.2-V to 3.6-V Power-Supply Range
- I_{off} Supports Partial-Power-Down Mode Operation
- I/Os Are 4.6-V Tolerant
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 8000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DESCRIPTION/ORDERING INFORMATION

This 16-bit noninverting bus transceiver uses two separate configurable power-supply rails. The SN74AVC16T245 is optimized to operate with $V_{\rm CCA}/V_{\rm CCB}$ set at 1.4 V to 3.6 V. It is operational with $V_{\rm CCA}/V_{\rm CCB}$ as low as 1.2 V. The A port is designed to track $V_{\rm CCA}$. $V_{\rm CCA}$ accepts any supply voltage from 1.2 V to 3.6 V. The B port is designed to track $V_{\rm CCB}$. $V_{\rm CCB}$ accepts any supply voltage from 1.2 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.2-V, 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

DGG OR DGV PACKAGE (TOP VIEW)

1DIR[1 \	ار 48	1 <u>OE</u>
1B1 [2	47] 1A1
1B2 [3	46	1A2
GND[4	45	GND
1B3 [5	44] 1A3
1B4 [6	43] 1A4
V _{CCB} [7	42] V _{CCA}
1B5 [8	41] 1A5
1B6 [9	40] 1A6
GND[10	39] GND
1B7 [11	38] 1A7
1B8 [12	37] 1A8
2B1 [13	36] 2A1
2B2 [14	35] 2A2
GND[15	34] GND
2B3 [16	33] 2A3
2B4 [17	32] 2A4
V _{CCB} [18	31	V _{CCA}
2B5 [19	30] 2A5
2B6 [20	29] 2A6
GND[21	28] GND
2B7 [22	27	2A7
2B8 [23	26	2A8
2DIR [24	25	2 <u>OE</u>
			1

The SN74AVC16T245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the outputs so the buses effectively are isolated.

The SN74AVC16T245 is designed so that the control pins (1DIR, 2DIR, 1OE, and 2OE) are supplied by V_{CCA}.

ORDERING INFORMATION

T _A	PACKAGE	(1)	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	TSSOP - DGG	Tape and reel	SN74AVC16T245DGGR	AVC16T245	
–40°C to 85°C	TVSOP – DGV	Tape and reel	SN74AVC16T245DGVR	WF245	
-40°C 10 85°C	VFBGA – GQL	Tone and real	SN74AVC16T245GQLR	WITO 4F	
	VFBGA – ZQL (Pb-free)	Tape and reel	SN74AVC16T245ZQLR	WF245	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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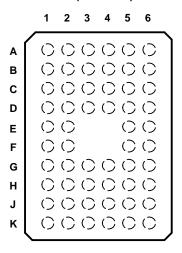
DESCRIPTION/ORDERING INFORMATION (CONTINUED)

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The V_{CC} isolation feature ensures that if either V_{CC} input is at GND, both ports are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

GQL OR ZQL PACKAGE (TOP VIEW)



TERMINAL ASSIGNMENTS(2)

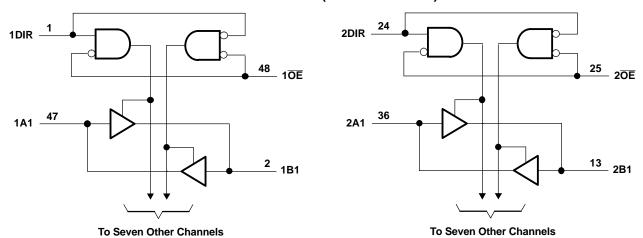
	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1 OE
В	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	V _{CCB}	V _{CCA}	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
E	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
Н	2B5	2B6	V _{CCB}	V _{CCA}	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2 OE

⁽²⁾ NC - No internal connection

FUNCTION TABLE (EACH 8-BIT SECTION)

INP	UTS	OPERATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Χ	Isolation

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CCA} V_{CCB}$	Supply voltage range		-0.5	4.6	V
		I/O ports (A port)	-0.5	4.6	
VI	Input voltage range ⁽²⁾	I/O ports (B port)	-0.5	4.6	V
		Control inputs	-0.5	4.6	
V	Voltage range applied to any output	A port	-0.5	4.6	V
Vo	in the high-impedance or power-off state (2)	B port	-0.5	4.6	V
M	Valta and an analysis of the provided that have been provided as (2)(3)	A port	-0.5	V _{CCA} + 0.5	V
Vo	Voltage range applied to any output in the high or low state (2)(3)	B port	-0.5	V _{CCB} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V _{CCA} , V _{CCB} , and GND			±100	mA
		DGG package		70	
θ_{JA}	Package thermal impedance (4)	DGV package		58	°C/W
		GQL/ZQL package		42	
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

⁽²⁾ The input voltage and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.



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Recommended Operating Conditions (1)(2)(3)

			V _{CCI}	V _{cco}	MIN	MAX	UNIT
V _{CCA}	Supply voltage				1.2	3.6	V
V _{CCB}	Supply voltage				1.2	3.6	V
			1.2 V to 1.95 V		V _{CCI} × 0.65		
V_{IH}	High-level input voltage	Data inputs ⁽⁴⁾	1.95 V to 2.7 V		1.6		V
	input voltage		2.7 V to 3.6 V		2		
			1.2 V to 1.95 V			$V_{CCI} \times 0.35$	
V_{IL}	Low-level input voltage	Data inputs ⁽⁴⁾	1.95 V to 2.7 V			0.7	V
	input voltage		2.7 V to 3.6 V			0.8	
			1.2 V to 1.95 V		$V_{CCA} \times 0.65$		
V_{IH}	High-level input voltage	DIR (referenced to V _{CCA}) ⁽⁵⁾	1.95 V to 2.7 V		1.6		V
	input voltage	iput voltage (referenced to v _{CCA})			2		
			1.2 V to 1.95 V			$V_{CCA} \times 0.35$	
V_{IL}	Low-level input voltage	DIR (referenced to V _{CCA}) ⁽⁵⁾	1.95 V to 2.7 V			0.7	V
		(referenced to ACCV)	2.7 V to 3.6 V			0.8	
V _I	Input voltage	<u> </u>			0	3.6	V
17	Outrut valtage	Active state			0	V _{cco}	1/
V_O	Output voltage	3-state			0	3.6	V
		<u> </u>		1.2 V		-3	
				1.4 V to 1.6 V		-6	
I_{OH}	High-level output curr	ent		1.65 V to 1.95 V		-8	mA
				2.3 V to 2.7 V		-9	
				3 V to 3.6 V		-12	
				1.2 V		3	
				1.4 V to 1.6 V		6	
I_{OL}	Low-level output curre	ent		1.65 V to 1.95 V		8	mA
	JL 25.1. 3701 34. PAR OUT OF			2.3 V to 2.7 V		9	
				3 V to 3.6 V		12	
Δt/Δν	Input transition rise or	fall rate				5	ns/V
T _A	Operating free-air ten	perature			-40	85	°C

⁽¹⁾ V_{CCI} is the V_{CC} associated with the data input port.
(2) V_{CCO} is the V_{CC} associated with the output port.
(3) All unused data inputs of the device must be held at V_{CCI} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
(4) For V_{CCI} values not specified in the data sheet, V_{IH} min = V_{CCI} × 0.7 V, V_{IL} max = V_{CCI} × 0.3 V.
(5) For V_{CCA} values not specified in the data sheet, V_{IH} min = V_{CCA} × 0.7 V, V_{IL} max = V_{CCA} × 0.3 V.

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Electrical Characteristics (1)(2)

over recommended operating free-air temperature range (unless otherwise noted)

DAD	AMETER	TEST COND	TIONS	V	V	T,	_A = 25°C		–40°C to 8	5°C	UNIT
FARA	AIVIETER	TEST CONDI	TIONS	V _{CCA}	V _{CCB}	MIN	TYP	MAX	MIN	MAX	UNIT
		$I_{OH} = -100 \mu A$		1.2 V to 3.6 V	1.2 V to 3.6 V				V _{CCO} - 0.2		
		$I_{OH} = -3 \text{ mA}$		1.2 V	1.2 V		0.95				
.,		$I_{OH} = -6 \text{ mA}$	$V_I = V_{IH}$	1.4 V	1.4 V				1.05		V
V _{OH}		$I_{OH} = -8 \text{ mA}$	$v_I = v_{IH}$	1.65 V	1.65 V				1.2		V
		$I_{OH} = -9 \text{ mA}$		2.3 V	2.3 V				1.75		
		$I_{OH} = -12 \text{ mA}$		3 V	3 V				2.3		
		I_{OL} = 100 μ A		1.2 V to 3.6 V	1.2 V to 3.6 V					0.2	
		$I_{OL} = 3 \text{ mA}$		1.2 V	1.2 V		0.15				
V _{OL}		$I_{OL} = 6 \text{ mA}$	$V_I = V_{IL}$	1.4 V	1.4 V					0.35	V
OL		$I_{OL} = 8 \text{ mA}$	VI = VIL	1.65 V	1.65 V					0.45	V
		$I_{OL} = 9 \text{ mA}$		2.3 V	2.3 V					0.55	
		I _{OL} = 12 mA		3 V	3 V					0.7	
I	Control inputs	$V_I = V_{CCA}$ or GN	D	1.2 V to 3.6 V	1.2 V to 3.6 V		±0.025	±0.25		±1	μΑ
	A or B port	V_{I} or $V_{O} = 0$ to 3.6 V		0 V	0 to 3.6 V		±0.1	±2.5		±5	A
off	A or B port	$V_1 \cup V_0 = 0 \cup 3$	0.0 V	0 to 3.6 V	0 V		±0.5	±2.5		±5	μА
oz ⁽³⁾	A or B port	$V_O = V_{CCO}$ or G $V_I = V_{CCI}$ or GN $\overline{OE} = V_{IH}$	ND, D,	3.6 V	3.6 V		±0.5	±2.5		±5	μΑ
				1.2 V to 3.6 V	1.2 V to 3.6 V					25	
CCA		$V_I = V_{CCI}$ or GN $I_O = 0$	D,	0 V	3.6 V					-5	μΑ
		10 = 0		3.6 V	0 V					25	
				1.2 V to 3.6 V	1.2 V to 3.6 V					25	
ССВ		$V_I = V_{CCI}$ or GN $I_C = 0$	D,	0 V	3.6 V					25	μΑ
		10 = 0		3.6 V	0 V					- 5	
CCA +	I _{CCB}	$V_I = V_{CCI}$ or GN $I_O = 0$	D,	1.2 V to 3.6 V	1.2 V to 3.6 V					45	μΑ
C _i	Control inputs	V _I = 3.3 V or GN	ND	3.3 V	3.3 V		3.5				pF
C _{io}	A or B	V _O = 3.3 V or G	ND	3.3 V	3.3 V		7				pF

 ⁽¹⁾ V_{CCO} is the V_{CC} associated with the output port.
 (2) V_{CCI} is the V_{CC} associated with the input port.
 (3) For I/O ports, the parameter I_{OZ} includes the input leakage current.

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Switching Characteristics

over recommended operating free-air temperature range, $V_{CCA} = 1.2 \text{ V}$ (see Figure 11)

PARAMETER	FROM	то	V _{CCB} = 1.2 V	V _{CCB} = 1.5 V	V _{CCB} = 1.8 V	V _{CCB} = 2.5 V	V _{CCB} = 3.3 V	UNIT		
FARAIVIETER	(INPUT)	(OUTPUT)	TYP	TYP	TYP	TYP	TYP	UNIT		
t _{PLH}	А	В	4.1	3.3	3	2.8	3.2	no		
t _{PHL}	A	Ь	4.1	3.3	3	2.8	3.2	ns		
t _{PLH}	В	Α	4.4	4	3.8	3.6	3.5	20		
t _{PHL}	Ь	A	4.4	4	3.8	3.6	3.5	ns		
t _{PZH}	ŌĒ	Α	6.4	6.4	6.4	6.4	6.4	ns		
t _{PZL}	OE	A	6.4	6.4	6.4	6.4	6.4	115		
t _{PZH}	ŌĒ	В	6	4.6	4	3.4	3.2	20		
t _{PZL}	OL	В	6	4.6	4	3.4	3.2	ns		
t _{PHZ}	ŌĒ	Α	6.6	6.6	6.6	6.6	6.8	ns		
t _{PLZ}	OE	A	6.6	6.6	6.6	6.6	6.8	115		
t _{PHZ}	<u>OE</u>	D	6	4.9	4.9	4.2	5.3	nc		
t _{PLZ}	ŌĒ	ŌĒ	ŌĒ	В —	6	4.9	4.9	4.2	5.3	ns

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 1.5 V \pm 0.1 V (see Figure 11)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = 1.2 V	V _{CCB} = ± 0. 1	1.5 V I V	V _{CCB} = ± 0.1		V _{CCB} = ± 0.2		V _{CCB} = ± 0.3		UNIT										
	(INFOT)	(001701)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX											
t _{PLH}	۸	В	3.6	0.5	6.2	0.5	5.2	0.5	4.1	0.5	3.7	20										
t _{PHL}	Α	В	3.6	0.5	6.2	0.5	5.2	0.5	4.1	0.5	3.7	ns										
t _{PLH}	В	Α	3.3	0.5	6.2	0.5	5.9	0.5	5.6	0.5	5.5	20										
t _{PHL}	В	A	3.3	0.5	6.2	0.5	5.9	0.5	5.6	0.5	5.5	ns										
t _{PZH}	ŌĒ	Α	4.3	1	10.1	1	10.1	1	10.1	1	10.1	20										
t _{PZL}	OE	A	4.3	1	10.1	1	10.1	1	10.1	1	10.1	ns										
t _{PZH}	ŌĒ	В	5.6	1	10.1	0.5	8.1	0.5	5.9	0.5	5.2	20										
t _{PZL}	OE	Ь	5.6	1	10.1	0.5	8.1	0.5	5.9	0.5	5.2	ns										
t _{PHZ}	CE	Α	4.5	1.5	9.1	1.5	9.1	1.5	9.1	1.5	9.1	20										
t_{PLZ}	ŌĒ	A	4.5	1.5	9.1	1.5	9.1	1.5	9.1	1.5	9.1	ns										
t _{PHZ}	OE .	В	5.5	1.5	8.7	1.5	7.5	1	6.5	1	6.3	20										
t _{PLZ}	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	D	5.5	1.5	8.7	1.5	7.5	1	6.5	1	6.3	ns

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Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 1.8 V \pm 0.15 V (see Figure 11)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = 1.2 V	V _{CCB} = ± 0.1		V _{CCB} = ± 0.1		V _{CCB} = ± 0.2		V _{CCB} = ± 0.3		UNIT				
	(INFOI)	(001701)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX					
t _{PLH}	Α	В	3.4	0.5	5.9	0.5	4.8	0.5	3.7	0.5	3.3	ne				
t _{PHL}	A	А	А	А	А	Б	3.4	0.5	5.9	0.5	4.8	0.5	3.7	0.5	3.3	ns
t _{PLH}	В	Α	3	0.5	5.2	0.5	4.8	0.5	4.5	0.5	4.4	ns				
t _{PHL}	В	^	3	0.5	5.2	0.5	4.8	0.5	4.5	0.5	4.4	115				
t _{PZH}	ŌĒ	Α	3.4	1	7.8	1	7.8	1	7.8	1	7.8	ns				
t _{PZL}	OE	A	3.4	1	7.8	1	7.8	1	7.8	1	7.8	115				
t _{PZH}	ŌĒ	В	5.4	1	9.2	0.5	7.4	0.5	5.3	0.5	4.5	ns				
t _{PZL}	OL	В	5.4	1	9.2	0.5	7.4	0.5	5.3	0.5	4.5	115				
t _{PHZ}	OE	^	4.2	1.5	7.7	1.5	7.7	1.5	7.7	1.5	7.7	ns				
t_{PLZ}	OE	Α	4.2	1.5	7.7	1.5	7.7	1.5	7.7	1.5	7.7	115				
t _{PHZ}	ŌĒ	ŌĒ	В	D	5.2	1.5	8.4	1.5	7.1	1	5.9	1	5.7	ne		
t _{PLZ}			Б	5.2	1.5	8.4	1.5	7.1	1	5.9	1	5.7	ns			

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 2.5 V \pm 0.2 V (see Figure 11)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = 1.2 V	V _{CCB} = ± 0.4	1.5 V 1 V	V _{CCB} = ± 0.1	1.8 V 5 V	V _{CCB} = ± 0.2		V _{CCB} = ± 0.3		UNIT													
	(INFOT)	(001701)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX														
t _{PLH}	Α	В	3.2	0.5	5.6	0.5	4.5	0.5	3.3	0.5	2.8														
t _{PHL}	А	В	3.2	0.5	5.6	0.5	4.5	0.5	3.3	0.5	2.8	ns													
t _{PLH}	В	А	2.6	0.5	4.1	0.5	3.7	0.5	3.3	0.5	3.2														
t _{PHL}	D	A	2.6	0.5	4.1	0.5	3.7	0.5	3.3	0.5	3.2	ns													
t _{PZH}	ŌĒ	Α	2.5	0.5	5.3	0.5	5.3	0.5	5.3	0.5	5.3	20													
t _{PZL}	OE	OE A	2.5	0.5	5.3	0.5	5.3	0.5	5.3	0.5	5.3	ns													
t _{PZH}	ŌĒ	В	5.2	0.5	9.4	0.5	7.3	0.5	5.1	0.5	4.5														
t _{PZL}	OE	В	5.2	0.5	9.4	0.5	7.3	0.5	5.1	0.5	4.5	ns													
t _{PHZ}	OF.	^	3	1	6.1	1	6.1	1	6.1	1	6.1														
t _{PLZ}	ŌĒ	ŌĒ A	3	1	6.1	1	6.1	1	6.1	1	6.1	ns													
t _{PHZ}	ŌĒ	В	5	1	7.9	1	6.6	1	6.1	1	5.2	20													
t _{PLZ}		ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌE B	5	1	7.9	1	6.6	1	6.1	1	5.2

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Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 3.3 V \pm 0.3 V (see Figure 11)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = 1.2 V	V _{CCB} = ± 0.1	1.5 V I V	V _{CCB} = ± 0.1		V _{CCB} = ± 0.2		V _{CCB} = ± 0.3		UNIT				
	(INPUI)	(001701)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX					
t _{PLH}	А	В	3.2	0.5	5.5	0.5	4.4	0.5	3.2	0.5	2.7	no				
t _{PHL}	A	Ь	3.2	0.5	5.5	0.5	4.4	0.5	3.2	0.5	2.7	ns				
t _{PLH}	В	А	2.8	0.5	3.7	0.5	3.3	0.5	2.8	0.5	2.7	ns				
t _{PHL}	D	В	A	2.8	0.5	3.7	0.5	3.3	0.5	2.8	0.5	2.7	115			
t _{PZH}	ŌĒ	Α	2.2	0.5	4.3	0.5	4.2	0.5	4.1	0.5	4	no				
t _{PZL}	OE	OL A	2.2	0.5	4.3	0.5	4.2	0.5	4.1	0.5	4	ns				
t _{PZH}	ŌĒ	В	5.1	0.5	9.3	0.5	7.2	0.5	4.9	0.5	4	no				
t _{PZL}	OE	Ь	5.1	0.5	9.3	0.5	7.2	0.5	4.9	0.5	4	ns				
t _{PHZ}	oe	^	3.4	0.5	5	0.5	5	0.5	5	0.5	5	ns				
t_{PLZ}	ŌĒ	Α	3.4	0.5	5	0.5	5	0.5	5	0.5	5	115				
t _{PHZ}	ŌĒ	ŌĒ	ŌE B	4.9	1	7.7	1	6.5	1	5.2	0.5	5	no			
t _{PLZ}			ŌĒ	ŌĒ	ŌĒ	ŌĒ	ŌĒ	В	4.9	1	7.7	1	6.5	1	5.2	0.5

Operating Characteristics

 $T_A = 25^{\circ}C$

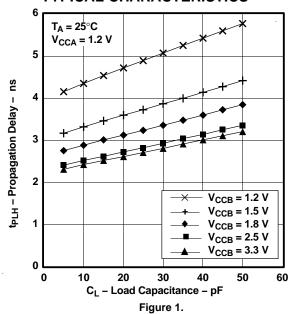
PARAMETER			TEST CONDITIONS	V _{CCA} = V _{CCB} = 1.2 V	V _{CCA} = V _{CCB} = 1.5 V	V _{CCA} = V _{CCB} = 1.8 V	V _{CCA} = V _{CCB} = 2.5 V	V _{CCA} = V _{CCB} = 3.3 V	UNIT	
				TYP	TYP	TYP	TYP	TYP		
	A to B	Outputs enabled	$C_L = 0$, f = 10 MHz, $t_r = t_f = 1 \text{ ns}$	1	1	1	1	2		
C _{pdA} ⁽¹⁾	AIOB	Outputs disabled		1	1	1	1	1	pF	
O _{pdA} (*)	B to A	Outputs enabled		13	13	14	15	16		
		Outputs disabled		1	1	1	1	1		
	A to B	Outputs enabled	$C_L = 0,$ f = 10 MHz, $t_r = t_f = 1 \text{ ns}$	13	13	14	15	16		
C (1)	AIOB	Outputs disabled		1	1	1	1	1		
C _{pdB} ⁽¹⁾	R to A	Outputs enabled		1	1	1	1	2	pF	
	B to A	Outputs disabled		1	1	1	1	1		

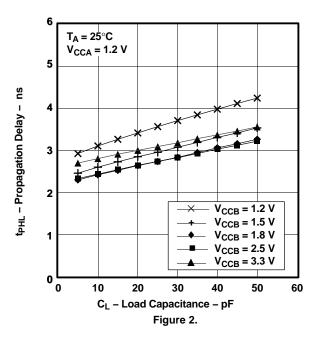
⁽¹⁾ Power dissipation capacitance per transceiver

Table 1. Typical Total Static Power Consumption ($I_{CCA} + I_{CCB}$)

V _{CCB}	V _{CCA}										
	0 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	UNIT				
0 V	0	<0.5	<0.5	<0.5	<0.5	<0.5					
1.2 V	<0.5	<1	<1	<1	<1	1					
1.5 V	<0.5	<1	<1	<1	<1	1					
1.8 V	<0.5	<1	<1	<1	<1	<1	μΑ				
2.5 V	<0.5	1	<1	<1	<1	<1					
3.3 V	<0.5	1	<1	<1	<1	<1					







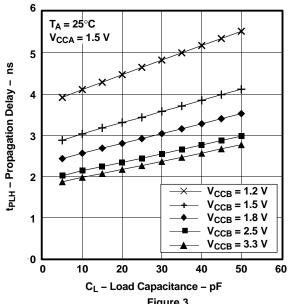


Figure 3.

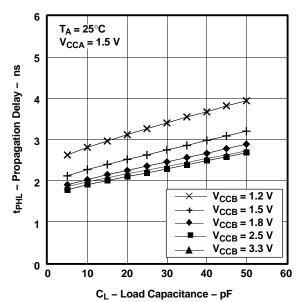
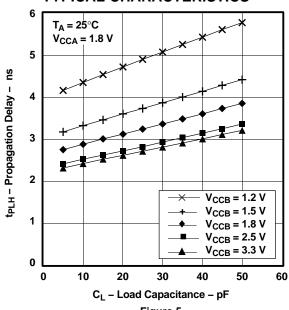


Figure 4.







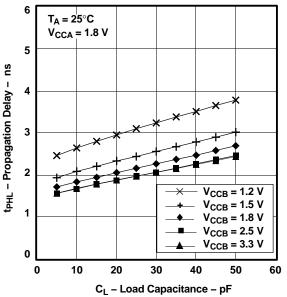
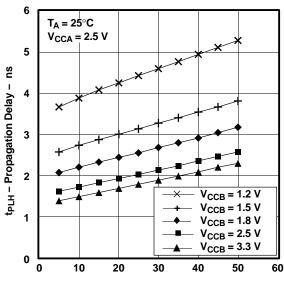
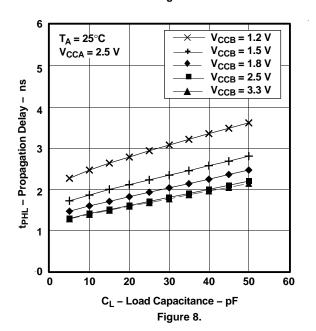


Figure 6.

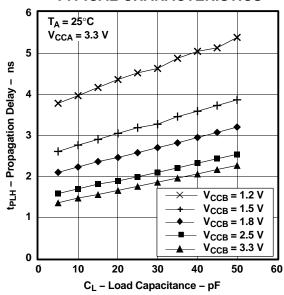




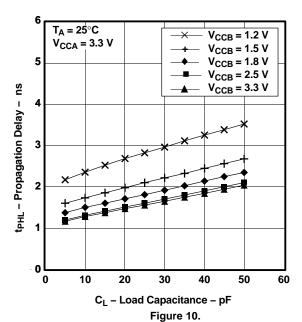
C_L – Load Capacitance – pF Figure 7.



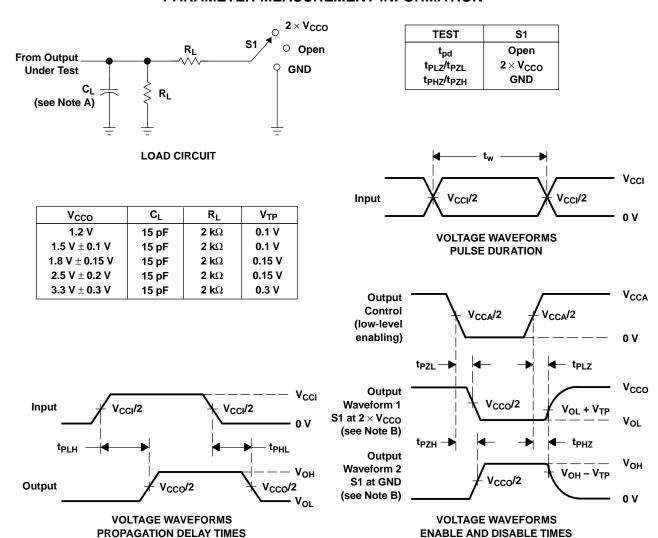








PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $dv/dt \geq 1 V/ns$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. V_{CCI} is the V_{CC} associated with the input port.
- I. V_{CCO} is the V_{CC} associated with the output port.

Figure 11. Load Circuit and Voltage Waveforms



3-Dec-2012

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Samples (Requires Login)
74AVC16T245DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74AVC16T245DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74AVC16T245DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74AVC16T245DGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
AVC16T245DGGR-D	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AVC16T245DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AVC16T245DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AVC16T245GQLR	OBSOLETE	BGA MICROSTAR JUNIOR	GQL	56		TBD	Call TI	Call TI	
SN74AVC16T245ZQLR	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

PACKAGE OPTION ADDENDUM



3-Dec-2012

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74AVC16T245:

Automotive: SN74AVC16T245-Q1

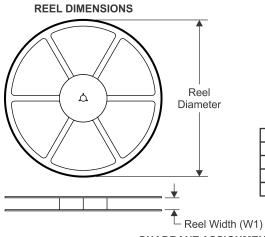
NOTE: Qualified Version Definitions:

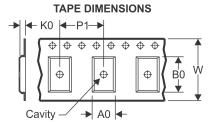
Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

www.ti.com 10-Oct-2012

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

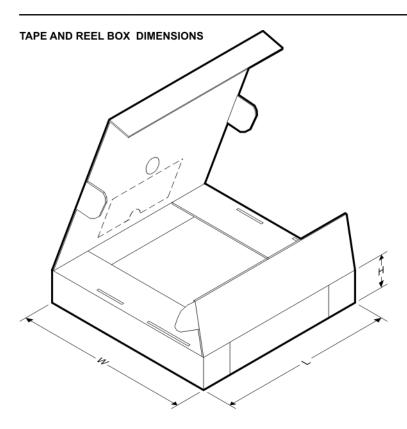
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AVC16T245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74AVC16T245DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74AVC16T245ZQLR	BGA MI CROSTA R JUNI OR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.5	8.0	16.0	Q1

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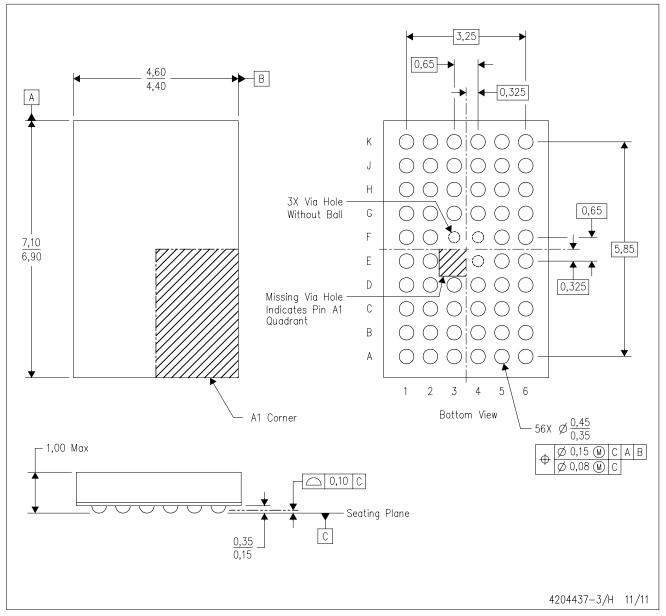


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AVC16T245DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74AVC16T245DGVR	TVSOP	DGV	48	2000	367.0	367.0	38.0
SN74AVC16T245ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	333.2	345.9	28.6

ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

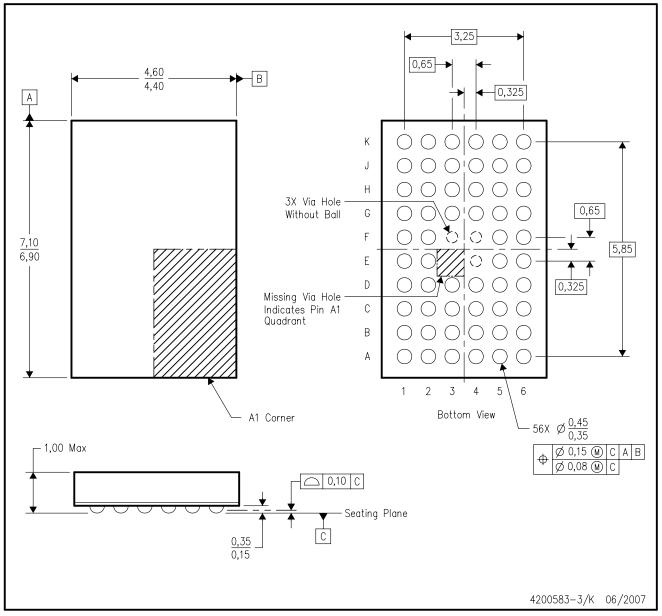
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-285 variation BA-2.
- D. This package is Pb-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).

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GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

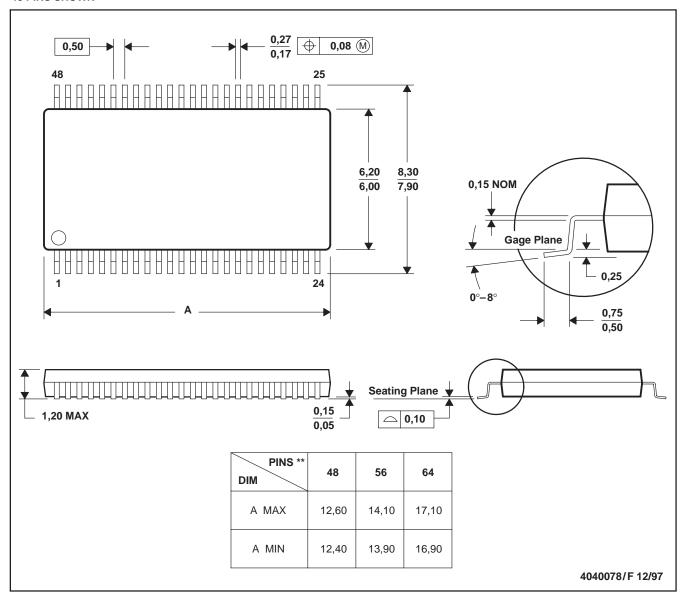
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-285 variation BA-2.
- D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.



DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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